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Preface

2016 3rd International Conference on Mechanics and Mechatronics Research (ICMMR 2016) will be held during June 15-17, 2016, in Chongqing China. This conference covered recent trends and progresses made in the field of mechanics and mechatronics research. The technical objective of this conference is to address key issues associated with science and technology in this rapidly evolving field of research and to promote contact between basic researchers and technological needs for real industrial applications. This event is intended as a vehicle for the dissemination of research results on latest advances made in the area of mechanics and mechatronics research, which gave an excellent opportunity for the scientists and researchers around the world to have a common platform to exchange their findings and to discuss the developments and make a base for starting collaborations in the national and international level. It was also aimed at promoting contacts amongst researchers and research groups for the creation of multinational thematic and research networks, as well as promoting contacts for future collaborative joint projects within some of the international funding programs.

The conference program offered invited, oral and poster presentations. The activities of the conference included invited speeches and author presentations in sessions. The invited talks were focused on the potential application of mechanics and mechatronics research in various fields of application.

ICMMR 2016 conference proceedings are addressing diverse topics related to recent trends in mechanics and mechatronics research. We hope the volume will offer the readers a good opportunity to access the state-of-the-art developments and future directions of researches on mechanics and mechatronics research.

We’re truly grateful to all the members of the conference committee, the reviewers who spared their valuable time, for their advice which have certainly helped to improve the quality, accuracy, relevance and the sincere efforts to maintain the quality of each paper selected for this conference program and volume for publication. And thank every author and participant who has contributed to the success of the conference.

Prof. Dan Zhang, York University, Canada

ICMMR 2016 Committees,
June, 2016
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